

XC18V00 Series PROMs

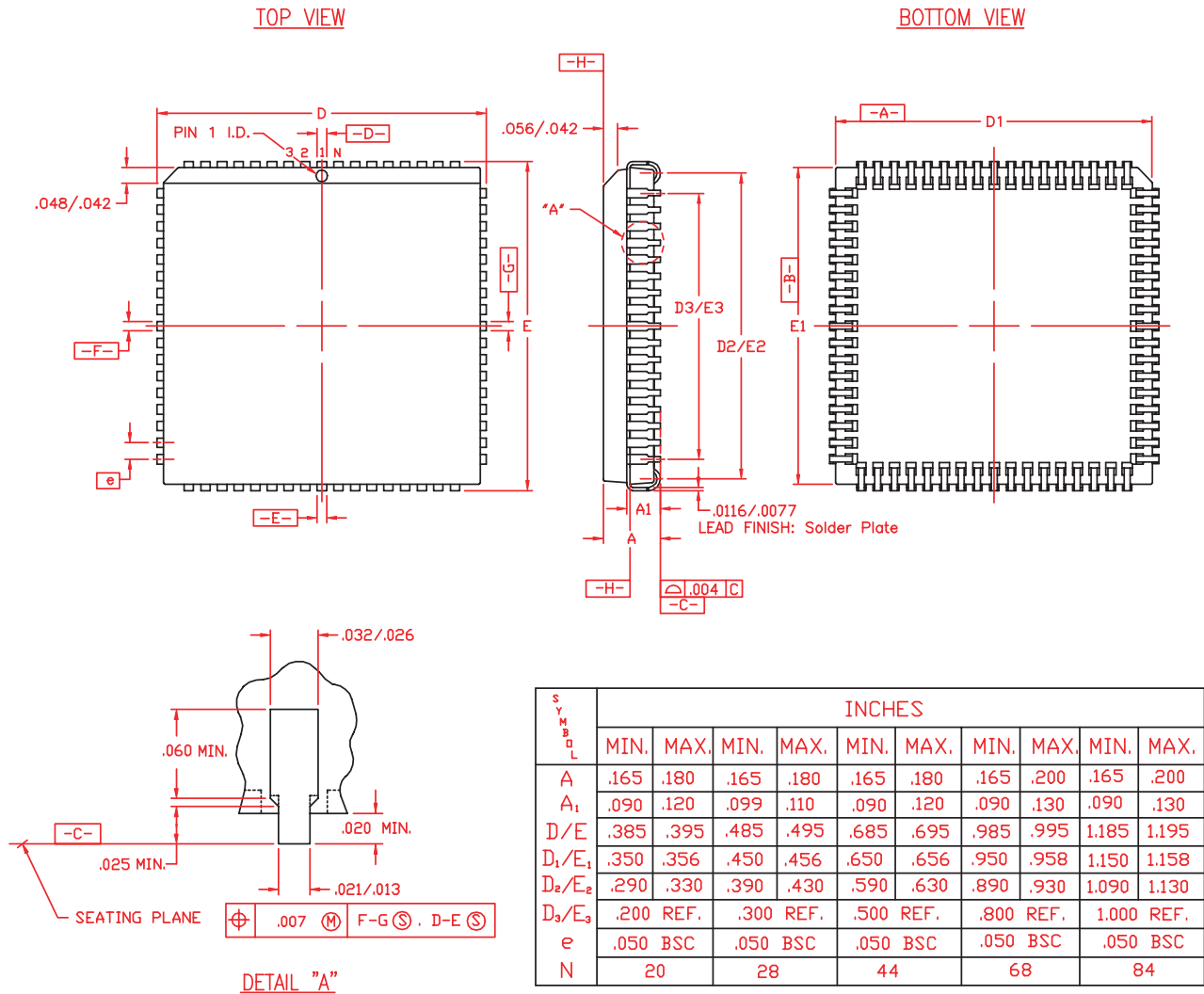
This appendix contains package specifications for the XC18V00 Series of In-System Programmable Configuration PROMs, as well as the XC18V00 Series product specification (DS026). The latest version of this information is available online (at www.xilinx.com).

PROM Package Specifications

This section contains specifications for the following Virtex-II packages:

- [PC20-84 Specification](#)
- [SO20 Specification](#)
- [SO8-VO8 Specification](#)
- [VQ44 Specification](#)

PC20-84 Specification



NOTES:

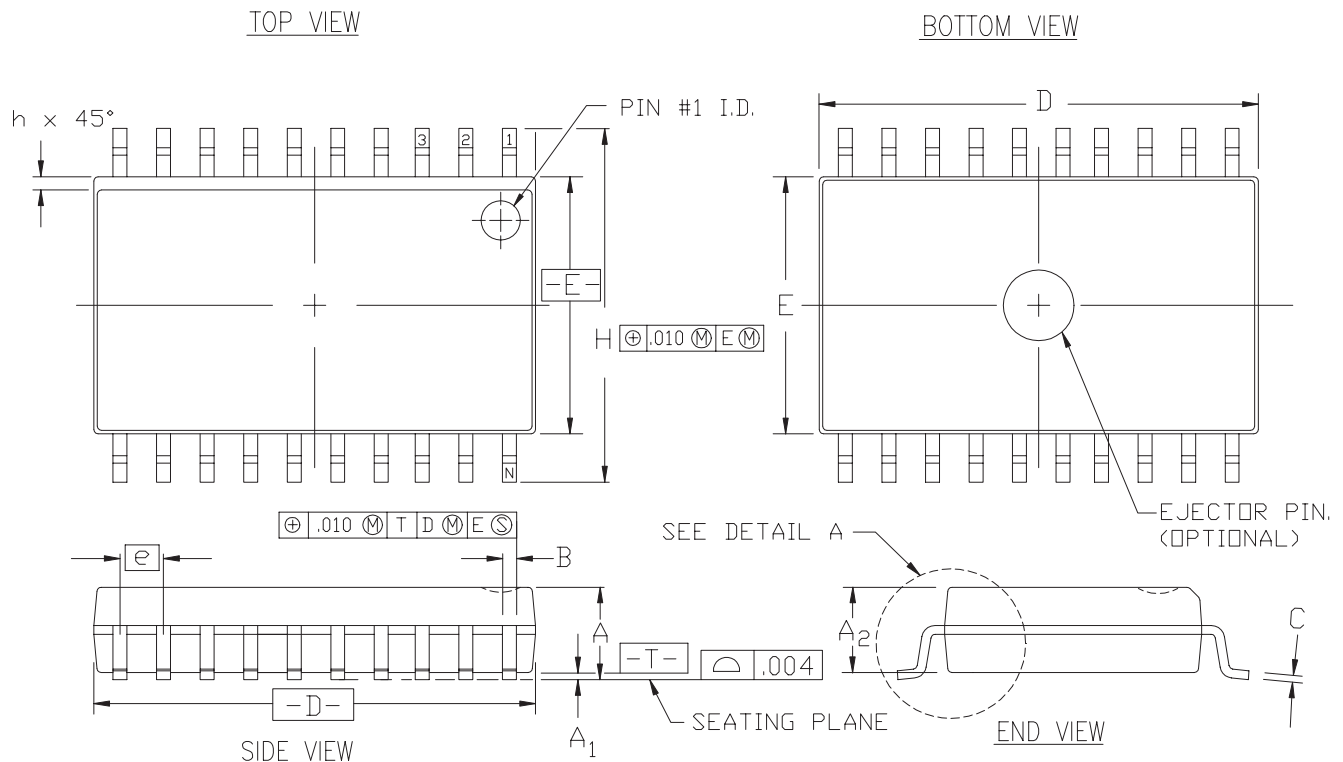
1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
2. DIMENSIONS 'D1' AND 'E1' DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010 PER SIDE.
3. 'N' IS NUMBER OF TERMINALS.
4. CONFORM TO JEDEC MO-047
5. TOP OF PACKAGE MAY BE SMALLER THAN BOTTOM BY .010".

20, 28, 44, 68 and 84-PIN PLCC (PC20 THRU PC84)

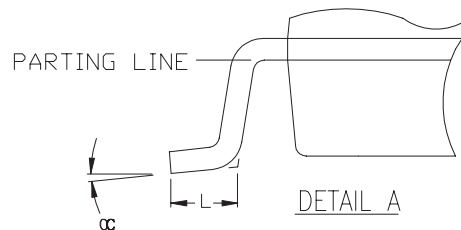
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Figure C-1: PC20-84 Specification

SO20 Specification



SYMBOL	INCHES		
	MIN.	NOM.	MAX.
A	.097	.101	.104
A ₁	.005	.009	.0115
A ₂	.090	.092	.094
B	.014	.016	.019
C	.0091	.010	.0125
D	.500	.505	.510
E	.292	.296	.299
e	.050 BSC		
H	.400	.406	.410
h	.010	--	.029
L	.024	.032	.040
α	0°	5°	8°



NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
2. DIMENSION "D" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
3. DIMENSION "E" DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010" PER SIDE.
4. LEAD FINISH: SOLDER PLATE
5. CONFORMS TO JEDEC MS-013-AC

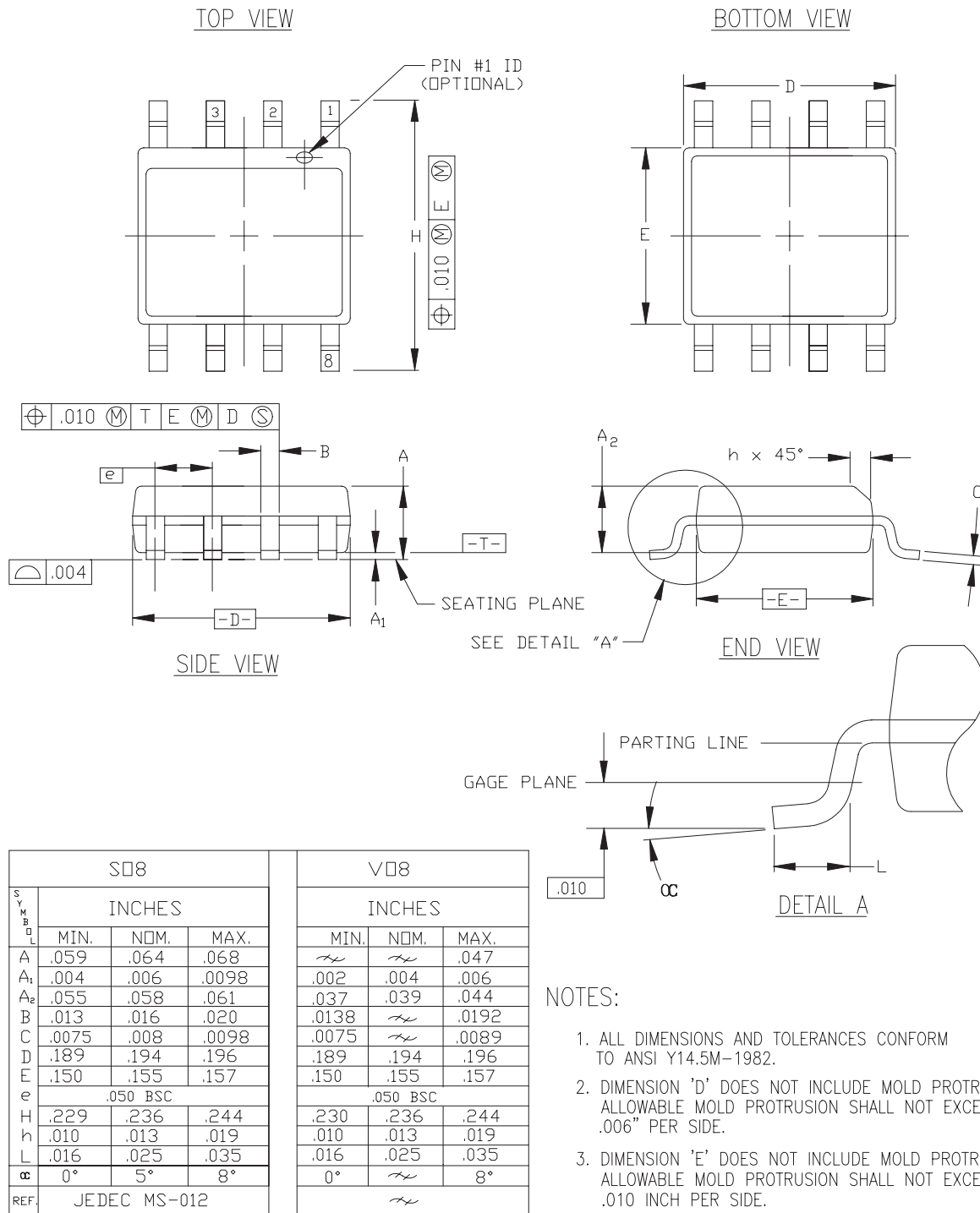


20 LEAD SOIC (SO20)

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Figure C-2: SO20 Specification

SO8-V08 Specification

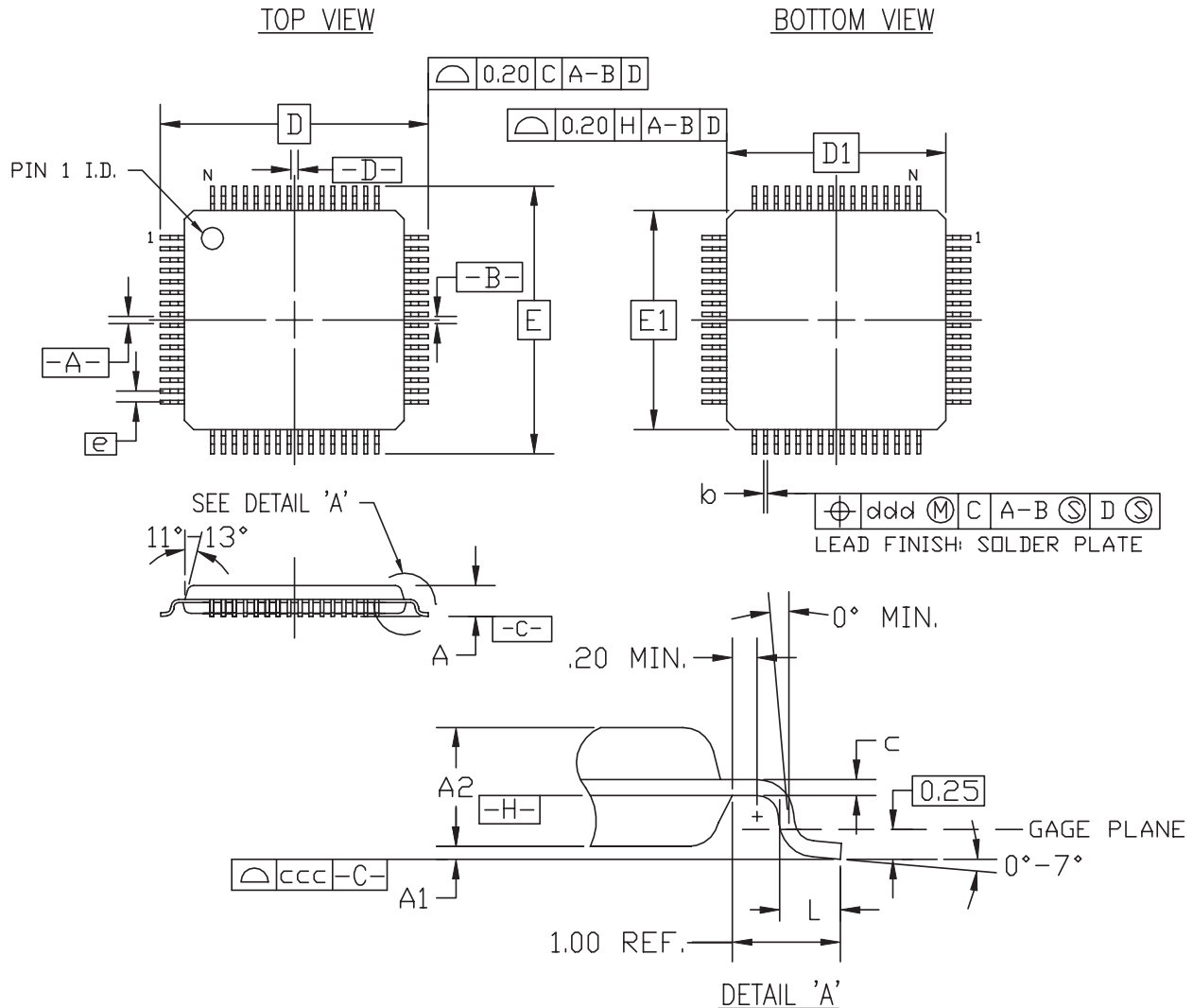


8 LEAD SOIC/TSOP (S08, V08)

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Figure C-3: SO8-V08 Specification

VQ44 Specification



SYMBOL	VQ44			VQ64			VQ100		
	MILLIMETERS			MILLIMETERS			MILLIMETERS		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	\approx	\approx	1.20	\approx	\approx	1.20	\approx	\approx	1.20
A ₁	0.05	\approx	0.15	0.05	0.10	0.15	0.05	0.10	0.15
A ₂	0.95	1.00	1.05	0.95	1.00	1.05	0.95	1.00	1.05
D/E	12.00 BSC			12.00 BSC.			16.00 BSC.		
D ₁ /E ₁	10.00 BSC			10.00 BSC.			14.00 BSC.		
b	0.30	0.37	0.45	0.17	0.22	0.27	0.17	0.22	0.27
c	0.09	\approx	0.20	0.09	\approx	0.20	0.09	\approx	0.20
e	0.80 BSC.			0.50 BSC.			0.50 BSC.		
L	0.45	0.60	0.75	0.45	0.60	0.75	0.45	0.60	0.75
ccc	\approx	\approx	0.10	\approx	\approx	0.08	\approx	\approx	0.08
ddd	\approx	\approx	0.20	\approx	\approx	0.08	\approx	\approx	0.08
N	44			64			100		
REF.	JEDEC MS-026-ACB			JEDEC MS-026-ACD			JEDEC MS-026-AED		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
2. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED 0.25mm PER SIDE.
3. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF PACKAGE BY 0.15mm.

44, 64, 100-PIN PLASTIC VERY THIN QFP (VQ44, VQ64, VQ100)

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Figure C-4: VQ44 Specification

